

Material		Al ₂ O ₃ , AlN
Layer count		Single layer and Double side
Max unit size		140*190mm
Profile Tolerance		+/-50um
Line/Space		75/75um
Min drill size		50um
Copper thickness		2-210um
Copper filling Aspect Ratio		5: 1
Copper peel strength		> 2N/mm(per IPC-TM-650 2.4.8)
Heat Resistance		350±10℃, 15min(per IPC-TM-650 2.4.7)
Solderability		> 95%(per IPC-TM-650 2.4.14)
Finish	ENIG	Au 1-5u", Ni 80-200u"
	OSP	
	ENEPIG	Ni:2-6um, Au:0.03um min, Pd:0.03um min
	Immersion Silver	0.15-0.45um